

# TM30P04D

# P -Channel Enhancement Mosfet

## General Description

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

## Applications

- Load switch
- PWM

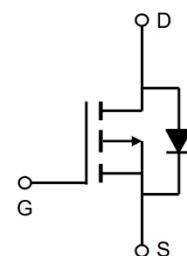
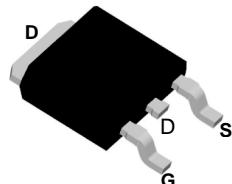
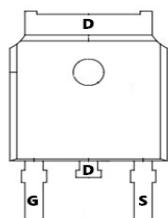
## General Features

$V_{DS} = -40V$   $I_D = -30A$   
 $R_{DS(ON)} = 25m\Omega$  (typ.) @  $V_{GS} = -10V$

100% UIS Tested  
100%  $R_g$  Tested



D:TO-252-3L



Marking: 30P04

## Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-30	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-22	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-112	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	40.9	mJ
$I_{AS}$	Avalanche Current	-30.0	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	35	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	3.6	$^\circ C/W$

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=-250\mu\text{A}$	-40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $\text{I}_D=-1\text{mA}$	---	-0.02	---	$\text{V}/^{\circ}\text{C}$
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=-10\text{V}$ , $\text{I}_D=-8\text{A}$	---	25	31	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-4\text{A}$	---	32	46	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=-250\mu\text{A}$	-1.0	1.5	-2.5	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	3.72	---	$\text{V}/^{\circ}\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-32\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^{\circ}\text{C}$	---	---	1	$\text{uA}$
		$\text{V}_{\text{DS}}=-32\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=55^{\circ}\text{C}$	---	---	5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=-5\text{V}$ , $\text{I}_D=-8\text{A}$	---	10.7	---	S
$\text{Q}_g$	Total Gate Charge (-4.5V)	$\text{V}_{\text{DS}}=-15\text{V}$ , $\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-1\text{A}$	---	11.5	---	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	3.5	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	3.3	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-15\text{V}$ , $\text{V}_{\text{GS}}=-10\text{V}$ , $\text{R}_G=3.3\Omega$ , $\text{I}_D=-1\text{A}$	---	22	---	ns
$\text{T}_r$	Rise Time		---	15.7	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	59	---	
$\text{T}_f$	Fall Time		---	5.5	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=-15\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1415	---	pF
$\text{C}_{\text{oss}}$	Output Capacitance		---	134	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	102	---	

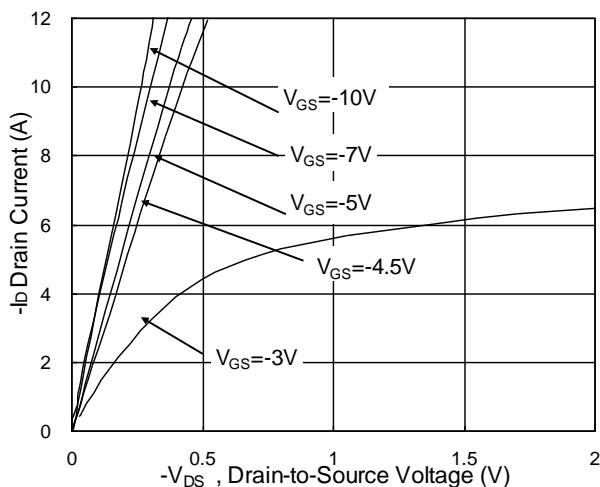
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sup>1,5</sup>	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	-30	A
$\text{I}_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	-60	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=-1\text{A}$ , $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

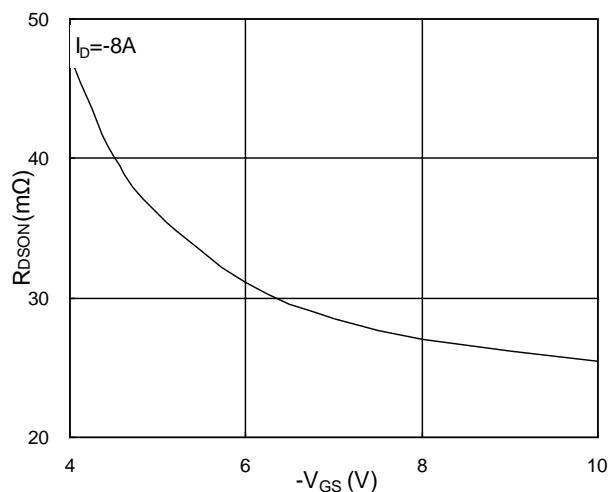
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=-25\text{V}$ , $\text{V}_{\text{GS}}=-10\text{V}$ , $\text{L}=0.1\text{mH}$ , $\text{I}_{\text{AS}}=-28.6\text{A}$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

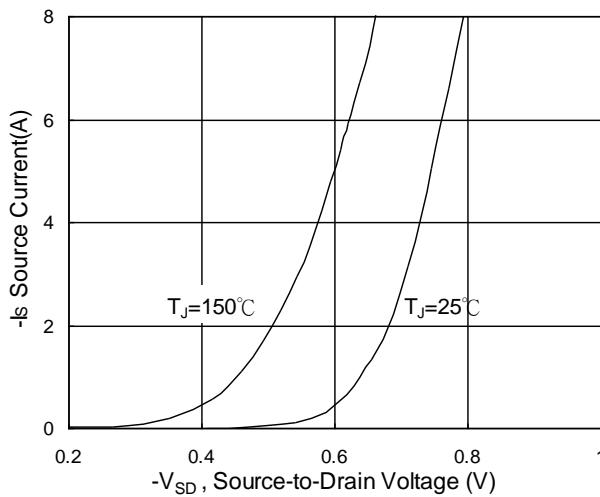
### Typical Characteristics



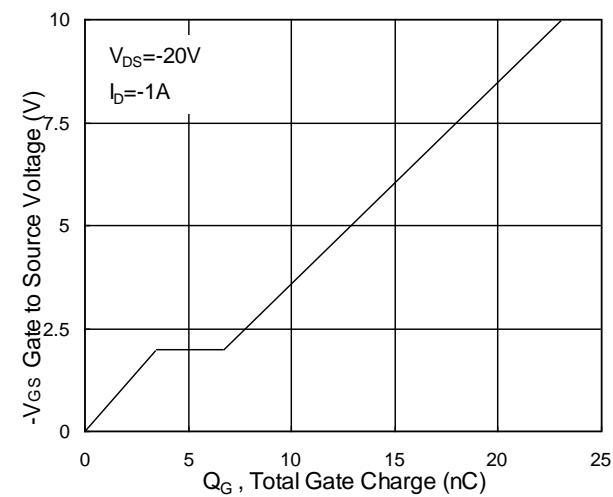
**Fig.1 Typical Output Characteristics**



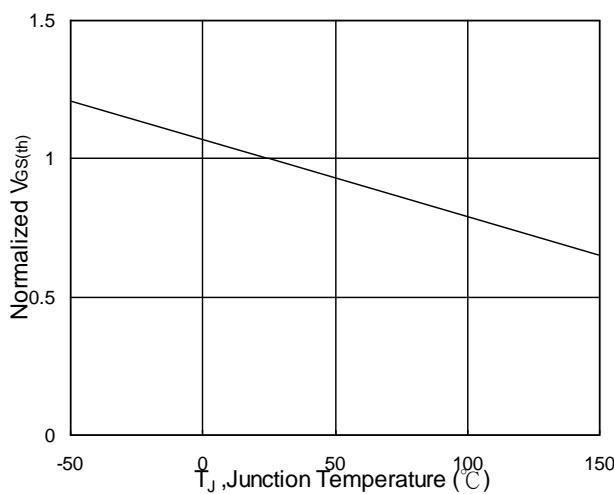
**Fig.2 On-Resistance v.s Gate-Source**



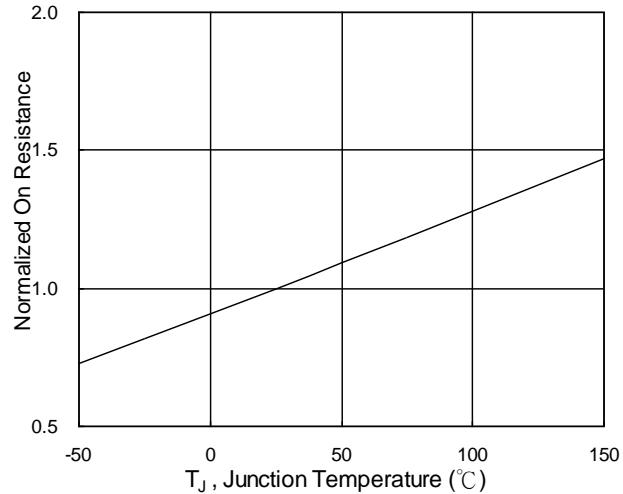
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate Charge Characteristics**



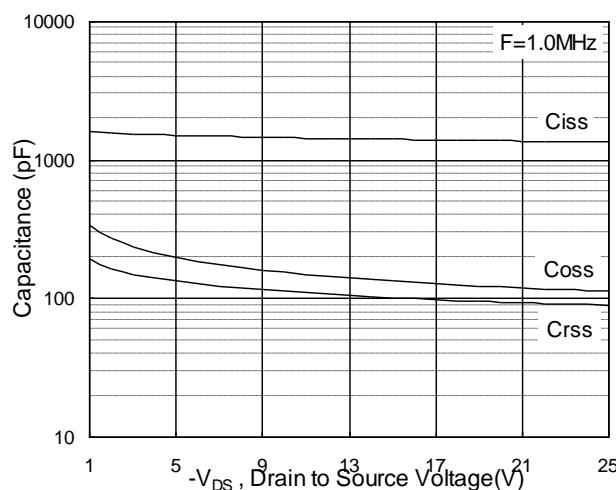
**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**



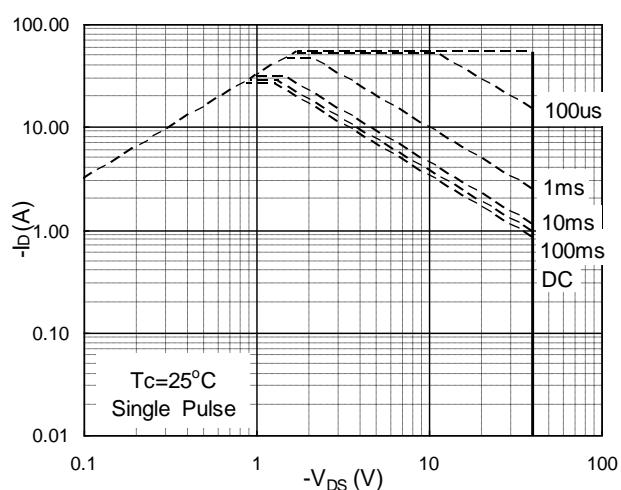
**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

**TM30P04D**

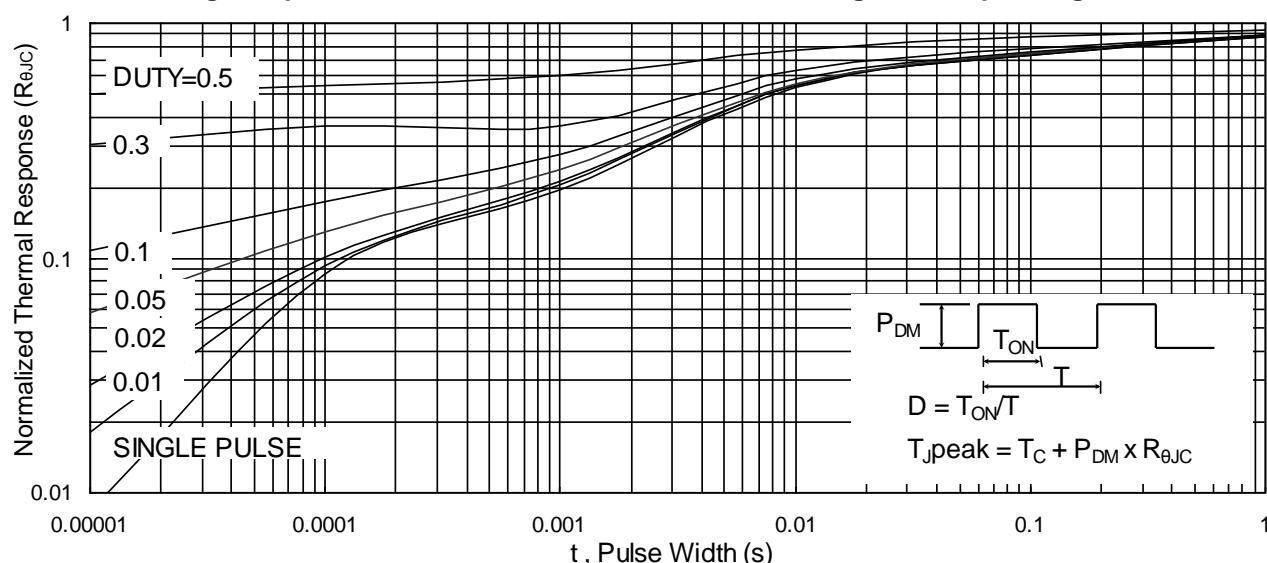
**P -Channel Enhancement Mosfet**



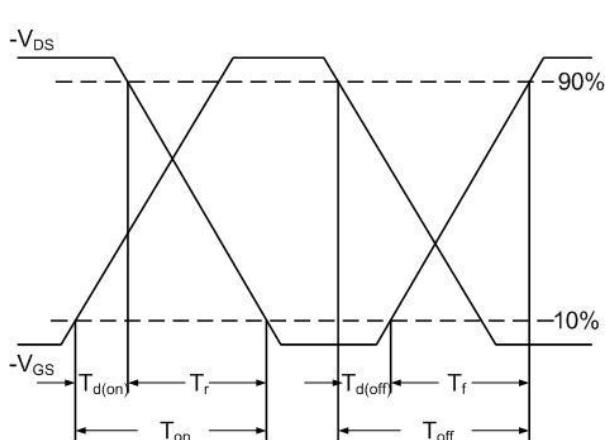
**Fig.7 Capacitance**



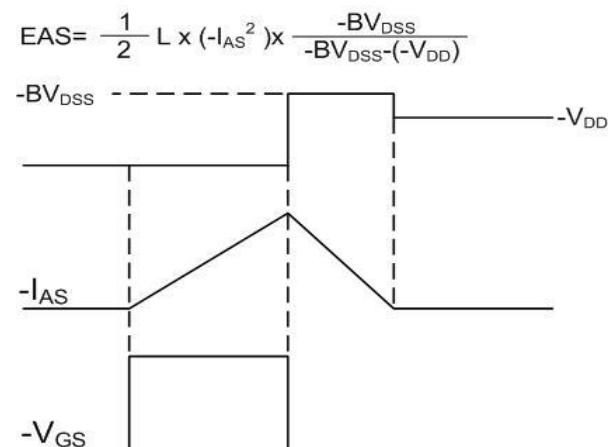
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

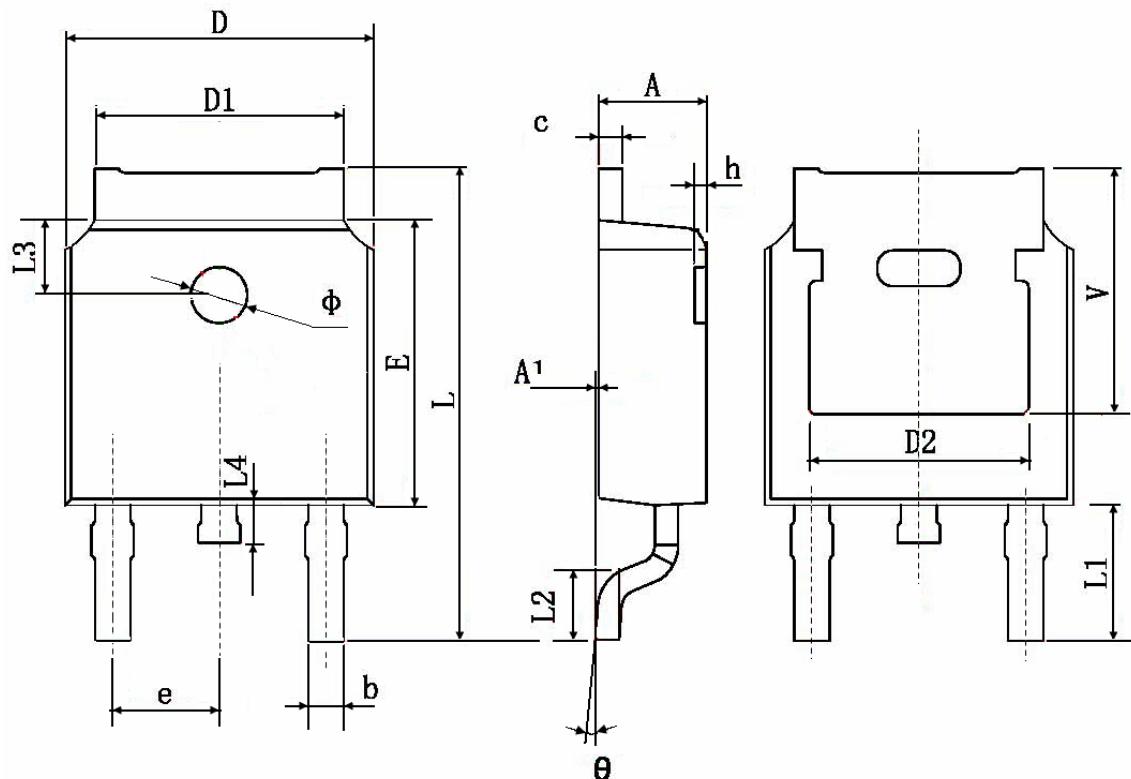


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

## Package Mechanical Data: TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	